

# WSK300

## 蓝宝石研磨机

WSK300 Sapphire Grinding Machine



NEW ENERGY SERIES 300-TYPE GRINDING MACHINE AUTOMATIC PARTS OF NEW ENERGY

机床轴径参数 Machine shaft diameter	50mm
机床轴径公差 Machine shaft tolerance	±0.005mm
行程 Stroke	800mm
厚度 Thickness	>0.2mm

主要参数 Main Parameters	
导轮直径 Guide wheel diameter	220mm
导轮轴距 Guide wheel base	440mm
导轮长度 Guide wheel length	330mm
导轮速度 Guide wheel speed	3000rpm
进给速度 Feed rate	0.01mm/100mm/min
摇摆角度 Swinging angle	±12°
切割方向 Cutting direction	沿工件长度方向/沿工件宽度方向
存储线面积 Storage wire area	~200cm <sup>2</sup>
存储容量 Storage capacity	2000L

能源系统 Energy system	
额定电压 Rated voltage	220/380V 50Hz
额定功率 Rated power	35kW
冷却液流量 Cooling liquid flow	12-17L/min

外形尺寸 Equipped size	
机床外形尺寸 (长*宽*高) Equipment size (L*W*H)	4600*2000*2000mm
机床重量 weight	12000kg

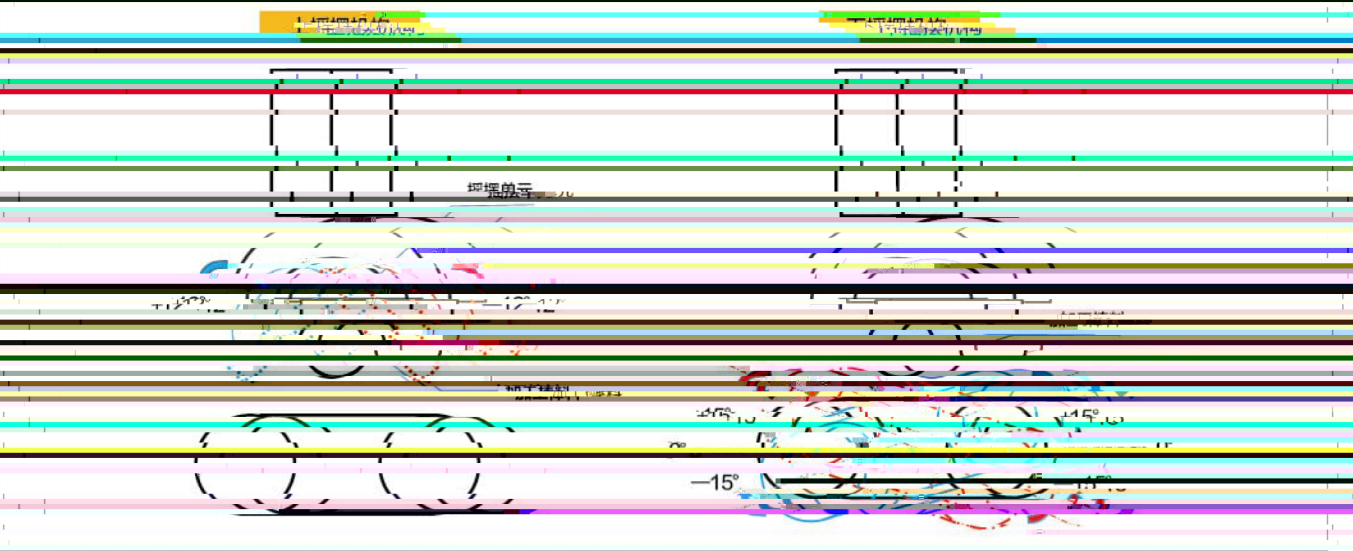
### 示意图 Schematic

### 设备用途与适用范围

- 本机床用于自动研磨蓝宝石等硬质脆性材料，如：硅、锗、石英玻璃、陶瓷、蓝宝石晶体等。
- 机床所有电器元件均采用国际知名品牌，保证机床的稳定性。
- 采用西门子伺服技术的一体化PC机，15"触摸屏。
- 电控柜配备温度监控系统，保证工件精度。
- 设备具备摇摆功能，可设置精确的摇摆角度，缩短了切割时间，并提高了晶片的产量。
- 滑轮数量最少化设计（仅6个滑轮），减少摩擦和磨损。

### 主要特点 Main Features

- This machine is used to automatically grind brittle and brittle materials using diamond tools, such as silicon, germanium, quartz, glass, ceramics, sapphire crystals, etc.
- All electrical components adopt international and famous brands to ensure the stability of the machine.
- Apply integrated PC of SIEMENS direction controlling system, 15" touch screen.
- The electric control cabinet is equipped with independent temperature control system to ensure the accurate operation of each component.
- The equipment has a swing function, which can set the accurate swing angle to shorten the cutting time and improve the yield of the wafer.
- Minimal design number of pulleys, which can reduce the wire distortion and fatigue.



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